

High thermally stable material for molding method

SUNCONNECT®

Ready-to-use



Organic-inorganic hybrid material

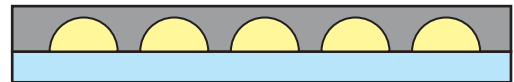
Solvent-free Resin

High Thermal Stability

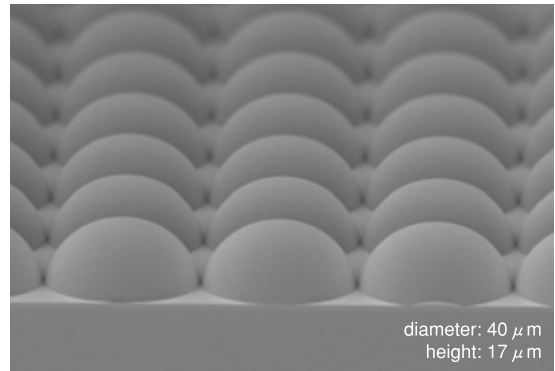
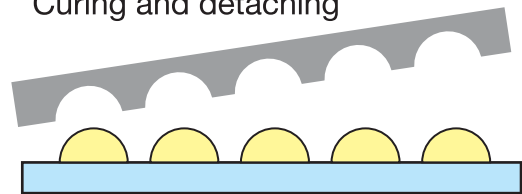
UV or Thermal Curing

Processability for molding

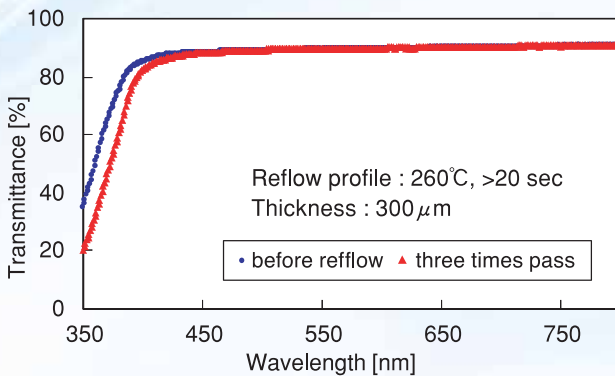
Filling and stamping



Curing and detaching



Yellowing resistance



Property catalogue

Item		Value	
Resin	Viscosity [mPa · s] (@20°C)	1,000~10,000	
	Curing condition	UV	10 mW/cm ² , 2 min
		Thermal	150°C, 60 min
Cured Material	Refractive index (@633nm)	1.52~1.60	
	CTE [ppm/K] (100~150°C)	70~110	
	5% Decomposition Temp.[°C] (in N ₂)	> 400	
	Thickness [μm]	~1,000	

Application

Reflow lens (imprint)

Relief structures

Other optical component

Our future vision = substitution of glass

Please contact us if you require any further information.